ABSTRACT

A test socket for an integrated circuit package includes a base for receiving the package, a pressure application subassembly which is pivotally rotated relative to the base portion, and a latching subassembly which is pivotally mounted to the opposite end of the base. The pressure application subassembly includes a plurality of trusses which pivot at one end about trunnions mounted to the base of the socket. The trusses carry spring-loaded rocker arms which hold the integrated circuit package in place. The socket also includes means for aligning the integrated circuit along one edge thereof and about its centerline.

-14-